

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	"048909".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/09 15:26
S2	4	"2003014926"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/09 15:27
S3	2	"20030141926"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/09 15:55
S4	5	"565569".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 14:51
S5	6	("20040246408" "6185032" "6762553").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 14:57
S6	0	"JP 5-315470"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 14:59
S7	2	"5-315470"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

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S8	18	("5107325" "5134724" "5442223" "5459368" "5491301" "5521419" "5535101" "5564096" "5789303" "5790213" "5811882" "5814848" "5841197" "5866943" "6134428" "6144080" "6180445").PN. OR ("6396144").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 14:59
S10	2	"4-142163"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:12
S11	205	toshitaka.in. and nec.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:14
S12	9	S11 and (multilayer or "multi-layer")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:17
S13	2	("5155655").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:22
S14	173	(multi\$1layer near2 (package or board)) and (power near2 (terminal or electrode)) and (ground\$3 near2 (terminal or electrode)) and (insulat\$3 or dielectric) and (capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:50
S15	199	((multi\$1layer near2 (package or board)) same (power near2 supply)) and (terminal or electrode) and (ground\$3) and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:51
S16	4794	257/300,532,535,700.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:46

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S17	3	"05315470"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:50
S18	62	(multi\$1layer near2 (wiring or board)) and ((insulat\$3 or dielectric) same (power near2 supply)) and (bypass near2 capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:57
S19	471	Tsuneoka.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:00
S20	2	S19 and (board and ground and power)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:26
S21	12	S19 and (ground and power)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:00
S22	2	"5355016".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:04
S23	45	("3614546" "4107555" "4567317" "4723156" "4909856" "5153379" "5166772").PN. OR ("5355016").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 18:17
S24	14	("5311059" "5355016" "5461545" "5541448" "5600181" "5601675" "5694300").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:19

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S25	20	("5153379" "5168772" "5311059" "6049469" "6388535" "6469380" "6483175" "6487088" "6512183" "6585149").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:26
S26	475	((printed multi\$3layer circuit) near2 (substrate or board)) and (power with ground\$3 with capacit\$4) and (ground\$3 with shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:42
S27	431	((printed multi\$3layer circuit) near2 (board)) and (power with ground\$3 with capacit\$4) and (ground\$3 with shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:38
S28	303	S26 and (power near2 (line pattern terminal electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:53
S29	1447	257/691.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:53
S30	8	S29 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:53
S31	15	S26 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 19:09
S32	242	S29 and (power near2 (line pattern conduct\$3 terminal electrode)) and ((printed circuit multi\$3layer) near2 (board or substrate)) and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 20:10

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S33	881	(power near2 (line pattern conduct\$3 terminal electrode)) and ((printed circuit multi\$3layer) near2 (board or substrate)) and (insulat\$3 or dielectric) and ((power and ground) near plane)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 20:10
S34	20613	(PCB or ((wiring or circuit) near board)) and (coaxial or coax)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:57
S35	6247	S34 and (power and ground)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:37
S36	35	S35 and ((power and ground) with (terminal and electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:38
S37	1081	(PCB or ((wiring or circuit) near board)) and (power with (supply plane)) and (power with (terminal or electrode)) and (ground\$3 with shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:59
S38	153	S37 and (external with power with connect\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 14:00
S39	121	S38 and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 14:02
S40	75	S39 and (power near2 (terminal or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 14:03

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S41	38	("20030194832" "20030197198" "20030198033" "20030202330" "4734819" "4754366" "4853826" "5022869" "5103283" "5212402" "5272590" "5306948" "5369058" "5403195" "5403784" "5438481" "5481436" "5483099" "5640048" "5692296" "5694297" "5717249" "5721673" "5734555" "5747875" "5831810" "5844419" "5892275" "5895966" "5956576" "6046911" "6222260" "6271607" "6342724" "6469895" "6489686" "6558181").PN. OR ("6885563").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/14 14:22
S42	205	toshitaka.in. and nec.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 17:33
S43	4800	257/300,532,535,700.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 17:33
S44	1448	257/691.cccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 17:34
S45	173	(multi\$1layer near2 (package or board)) and (power near2 (terminal or electrode)) and (ground\$3 near2 (terminal or electrode)) and (insulat\$3 or dielectric) and (capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 17:34
S46	199	((multi\$1layer near2 (package or board)) same (power near2 supply)) and (terminal or electrode) and (ground\$3) and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 17:34